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1998-12

**INTERNATIONAL ELECTROTECHNICAL COMMISSION
COMMISSION ELECTROTECHNIQUE INTERNATIONALE**

**TECHNICAL COMMITTEE NO. 3: DOCUMENTATION AND GRAPHICAL SYMBOLS
SUB-COMMITTEE NO. 3D: DATA SETS FOR LIBRARIES**

Unconfirmed Minutes of the meeting of SC3D on November 12th, 1998 in Charlottelund, Denmark.

Present:

Chairman: Dr. D.E. Radley (United Kingdom)

Secretary: Mr. P.G. van Reekum (Netherlands)

Central Office: Mr. R. Cordelier (Switzerland)

COUNTRY	DELEGATES	COUNTRY	DELEGATES
China	Mr. Zhang Hongtu	Japan	<u>Prof. Mikio Takagi</u> Mr. Satoshi Ito
Denmark	Mr. Regnar Schulz	Netherlands	<u>Mr. Arnold Gehner</u> Mr. Frans van Noesel
Finland	Mr. Tapio Viitanen		
France	Mr. Jacques Bodin		
Germany	<u>Mr. Juergen Bethman</u> Mr. Dietmar Borries Mr. Wolf-Dieter Kisselmann Mr. Fritz Reuter		

Observers:

U.S.A Somendra Sing

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I. Opening of the meeting

On behalf of the Danish National Committee, Mr. Schulz welcomed the delegates in Denmark and wished them a successful meeting.

The Chairman, Mr. Radley, opened the 8th meeting of SC3D, thanked the Danish National Committee for hosting the meeting and wished the delegates a good and constructive meeting. He introduced the new secretary, Mr. Peter van Reekum, and wished him good luck with the secretariat work. He thanked the past secretary, Mr. Frans van Noesel, for the excellent work he has done as secretary for the past 7 years.

Mr. Bethman announced that this is his last meeting as spokesman of the German delegation. He introduced Mr. Borries as his successor. The chairman thanked him for the work he has done in SC3D.

II. Approval of the (Revised) draft Agenda, document 3D/54/DA-1

The Chairman announced that a report will be given by Mr. Satoshi Ito under agenda item 5.5 regarding several projects running in Japan.

With this modification the agenda was approved.

III. To note the minutes of the meeting of SC3D held in New Delhi October the 23rd, 1997, document 3D/57/RM

There were no comments received on the minutes within three months after circulation.

Therefore the minutes were already confirmed according to the new rules of the Central Office.

The Chairman thanked the Secretary for preparing the minutes.

There were no actions arising from these minutes that were not covered by the agenda.

IV. To receive a report from the Chairman and Secretary regarding the harmonization of efforts and results with ISO TC184/SC4/WG2 'Part libraries', and possible implications on the work in both committees.

The report prepared for this meeting, **document 3D(Charlottelund/secretariat)02**, is attached as annex A to these minutes. The report was noted.

Mr. van Noesel gave some additional information to the report. He reported that during the last working group meeting Mr. Guy Pierra, convenor of ISO TC184/SC4/WG2, was consulted regarding some errors in clause 8 of IEC 61360-2 and the required extensions of the common EXPRESS model.

V. Status overview of the IEC 61360 documents: "Principles and methods for defining standard data element types with associated classification scheme for electric components".

5.1 61360-1: Definitions - Principles and methods

A proposal for the revision of this standard has been recently circulated as document 3D/64/CD, for more details see point 7 of the agenda.

5.2 61360-2: EXPRESS Dictionary schema

The Chairman informed the delegates that the IEC 61360-2 is published by May 1998.

Due to some errors in clause 8 the working group is working on a new version of this standard, for more details see point 7 of the agenda.

5.3 61360-3: Maintenance and Validation procedures

The chairman informed the delegates that Codus Ltd has decided not to continue acting as maintenance agency for the IEC reference collection (IEC 61360-4). The working group is studying on how to continue in the future, for more details see point 7 of the agenda.

5.4 61360-4: IEC Reference Collection of standard data element types, component classes and terms.

SC3D wishes to report to the Committee of action that they will issue a supplement to IEC 61360-4, for more detail see point 7 of the agenda.

5.5 Presentation by Mr. Satoshi Ito

Mr. Ito reported about projects running in Japan. The E-CALS project was ended in March 1998 and the efforts of standardization was continued by EIAJ until October 1998. A new project, ECALS-II, was started and will run through March 2000. Another project is ChemiCALS. The project is based on the IEC 61360 series and the classification will be extended with 62 classes and 200 new data element types will be requested to be defined. Mr. Ito will investigate whether this information can be made available in SPF format and if it can be used for inclusion in the IEC reference collection.

VI Report from Codus Ltd., the Maintenance Agency of the IEC Reference Collection of standard data element types, component classes and terms.

Due to the announcement of Codus Ltd., see item 5.3, there was nothing to report.

VII To receive a report from:

- **SC3D/WG1 - Classification and coding of component packages -, and**
- **SC3D/WG2 - Classification of components and definition of technical data elements, document 3D(Charlottelund/WG 1&2)05**

The Chairman thanked the secretary for preparing this report, attached as annex B to these minutes.

Working group 2 A committee draft for the revision of IEC 61360-1 has been send to the Central Office and will be circulated as document 3D/64/CD. The major changes and extensions in comparison to the existing standard are listed on the front page of the document.

Already comments have been received from the University of Hagen (Germany) who requested a link between the component classification tree and the geometry classification tree. A linking mechanism has been defined by the working group.

The comments received on the document will be discussed in the next working group meeting. The document will also be discussed with ISO TC184/SC4/WG2 to see what the impact of the modifications will be on the common EXPRESS model.

The errors discovered in clause 8 of IEC 6130-2 have been corrected. After consultation with the Central Office officer Mr. R. Cordelier it was decided to notify in the report to the Committee of Action that SC3D has planned to issue a new version of IEC 61360-2 based on the corresponding maintenance cycle in chapter E of the Strategic Policy Statement. The first step will be the circulation of a CDV at the beginning of 1999 containing the proposed new clause 8. The templates in this clause will be normative and the examples informative. After approval of the FDIS a complete new version of IEC 61360-2 will be published.

Since Codus Ltd has indicated that it will not be able to continue with the maintenance activities an interim solution was found in cooperation with the officer of the Central Office, Mr. J. Cordelier, for the maintenance and validation of IEC 61360-4. SC3D will notify in the report to the Committee of Action that they have planned to issue a supplement to IEC 61360-4 based on the corresponding maintenance cycle in chapter E of the Strategic Policy Statement. This supplement will contain known requests for the definitions of new data element types. The document will be circulated as a committee draft for voting and comments according to the normal procedures of the IEC.

A new letter was prepared by the working group and will be send to the secretaries of the IEC TCs and SCs asking for their cooperation in the validation process. The delegates are invited to discuss this letter in their National Committee and send their comments or remarks to the secretary before the 15th January 1998. SC3D will also propose in the report to the Committee of Action that it be made a requirement for TCs to assist in the validation process.

The possibility of a solution similar to the arrangements for the SC3A and SC3C databases was discussed. There is a difference in scale between the SC3A / SC3C and SC3D with 100 request per year for SC3A / SC3C and 5000 expected requests per year for SC3D. The main problem is the funding of the maintenance activities as it requires a considerable amount of manpower.

It was agreed to send a letter to the Committee of action and Sector Board 3 in which SC3D express its concern regarding the expected amount of work related to the maintenance activities of new requested data element types and the funding of these activities. Various avenues should be explored such as one or more National Committees performing the function or by finding funding from other sources in the European Union, Japan or the U.S.A.

Working group 1. Comments on document 3D/56/CD, Classification and coding of shapes of electric components for placement on printed wiring boards, were discussed in several working group meetings and will be implemented in a new second CD which will be circulated at the beginning of 1999.

VIII. Organization of future work

8.1 Activities of the SC3D Working Groups.

8.1.1 Working Group 1 -- "Classification and coding of component packages"

8.1.2 Working Group 2 -- "Classification of components and definition of technical data element types"

8.1.3 To discuss the need for the erection of additional working group(s)

Currently there are no plans for additional work within the existing Working Groups.

Both working groups have as much work as they can handle. The work will take certainly take all available capacity to get the planned CDs and CDVs circulated.

Mr. Cordelier stated that the new maintenance rules require a maintenance team to maintain the IEC 61360 series. It was agreed was that the working groups will act at the same time as the maintenance team for IEC 61360 series.

For the time being there is no foreseen need for new working groups to be established. It is expected that the existing Working Groups can take on the work for the immediate future.

IX To discuss the Strategic Policy Statement, document 3D(Charlottelund/secretariat)06

According the new rules of the Central Office the strategic policy statement has to be modified and extended in many places. The delegates agreed that the chairman and secretary would take care of this.

9.1 To discuss the Programme of work, document 3D/55/PW

As some of the documents referenced have been superseded, the Program of Works has to be updated. The secretary will send the updated information to the Central Office.

X Liaisons with:

- other Committees of IEC, ISO, CEN/CENELEC;
- SI2/ECIX (former Pinnacles)
- establishment of a liaison with E-Cals (part of N-Cals)

The proposal to have a formal liaison with ECALS was discussed. Mr. Takagi agreed to ask ECALS if they are interested in such a liaison.

Mr. Reuter asked for a liaison with ROSETTA. It was agreed to find out what the goals of this project are before making a decision.

XI Liaison reports from:

11.1 Frits Reuter on TC93, document 3/532/INF

The report of Mr. Reuter was noted and is attached as annex C to the minutes.

Mr. Reuter announced that he has to stop acting as liaison officer for TC93. Mr. T. Viitanen agreed to take over the liaison function.

11.2 Wolf-Dieter Kisselmann on CECC/WG-CAD - CIREP, document 3D(Charlottelund/Kisselmann)07

The report of Mr. Kisselmann was noted and is attached as annex D to the minutes.

11.3 Frans van Noesel on CENELEC TC217 and SI2/ECIX, document 3D(Charlottelund/vNoesel)08

The report of Mr. van Noesel was noted and is attached as annex E to the minutes.

XII To prepare a report for the TC3 meeting of October 24, 1997, document3(Charlottelund/SC3D)6.

It was agreed that the Chairman and the Secretary will produce this report.

XIII Any other business.

SC3B has asked which procedure they have to follow for a request for new data element types. If the requested data element types are within the scope of the competence of a technical committee this technical committee can act as validation group and validate the relevant data element types and then send them to the Validation Agency (TC3) for inclusion in the IEC reference collection according the rules in IEC 61360-3.

XIV Date and place of the next meeting.

The next SC3D meeting will be held in Kyoto (Japan), October 1999 in conjunction with the General meeting. For a complete time schedule see annex F
The meeting in 2000 would probably held in Stockholm (Sweden).

XV Closure of the meeting

The chairman thanked the delegates for their attendance and contribution to this meeting. He thanked the Danish National Committee and its staff once more for the facilities provided and the excellent secretariat support during the meeting.
His wished the delegates a safe journey home and closed the meeting.



Peter van Reekum
secretary IEC SC3D

Annex A



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3D(Charlottenlund/secretariat)02
November 1998

INTERNATIONAL ELECTROTECHNICAL COMMISSION

SUB-COMMITTEE NO. 3D: DATA SETS FOR LIBRARIES

Report from the ad-hoc Joint Working Group: IEC/SC3D -- ISO/TC184/SC4/WG2

Members of both SC's met each other on a regular base during the ISO/TC184/SC4 (STEP) meetings in January 1998 Orlando (USA), June 1998 Bad Aibling (Germany).

During these meetings the proposed adaptations to the IEC 61360 series of standards were discussed, especially regarding the common EXPRESS model.

A telephone meeting was held with Mr. G. Pierra, the convenor of Plib, during the SC3D working group meeting in October 1998 in Eindhoven. The wanted extensions of the common ISO/IEC EXPRESS information model were discussed.

As there are still points unclear Dr. Radley and Mr. Van Noesel will on short term in a face to face meeting with Mr. Pierra try to eliminate the existing differences in approach and to reach a common solution for the EXPRESS model.

We hope to continue the fruitful co-operation with the STEP Plib community.

A handwritten signature in black ink, appearing to read 'Peter van Reekum', written in a cursive style.

Peter van Reekum

Annex B



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3D(Charlottenlund/WG 1&2)05
November 1998

INTERNATIONAL ELECTROTECHNICAL COMMISSION

TECHNICAL COMMITTEE NO. 3: DOCUMENTATION AND GRAPHICAL SYMBOLS SUB-COMMITTEE NO.3D: DATA SETS FOR LIBRARIES

Report from Working Group 1 and 2

Report from the convenor of SC3D Working Group 1 - Classification and coding of component packages - and SC3D Working Group 2 - Classification of components and definition of technical data elements -.

1 scopes

1.1 WG1

To prepare standards for classification and coding of electric components according to key mechanical characteristics for use on printed wiring boards in design and mechanical handling.

1.2 WG2

Using existing definitions, terminology and practices to set standards to prepare definitions for technical data element types that can be used:

- to describe electric components;
- to establish subsets selected from the list of data elements suitable for characterizing individual component classes;
- to prepare a standard scheme for classification of components according to function and technology as appropriate.

2 Membership

No changes in the list of memberships since the meeting of SC3D in New Delhi , October 1997. The working group welcomed a new member as well as new corresponding members.

3 Work since New Delhi

Four meetings since the New Delhi meeting, January 1998 Eindhoven, March 1998 Eindhoven, July 1998 Sheffield and Eindhoven, September 1998. From these meetings informal notes from the convenor are available on demand.

It was decided that regarding the interaction between both working groups, to have for the time being joint meetings of both working groups.

After the restart of the work in the field of the classification of packages a new CD was issued. The received comments are incorporated in a new CD, that will be issued on short notice.

The work on the update of IEC 61360-1 was rounded in October 1998, and a new CD has been issued to be circulated by the Central Office.

A proposal was issued to extend the IEC 61360 series of standards. A new CD has been issued for comments.

4 Quotations from the notes of the SC3D working group 1&2 Charlottenlund meeting: working group 2:

The linking mechanism between the functional classification tree and the geometric tree as requested by the University of Hagen, Germany, was discussed and a solution defined.

The work about the corrigendum of IEC 61360-2, clause 8, was rounded in co-operation with ISO/TC184/Sc4/WG2, ECIX- and CIREP partners. Based on advises of CO officers, an official amendment to this part of IEC 61360-2 may be expected on short notice.

CODUS Ltd. Has indicated not to continue as acting maintenance agency for the IEC reference collection (61360-4). In co-operation with IEC officers an interim solution was defined for issuing new DETs to be included in the IEC reference collection based on the new maintenance team constructs of IEC.

A new letter to the secretaries of TCs and SCs has been prepared [document 3D(Charlottenlund/secretary)03] to ask for their co-operation in the validation process. It is proposed indicate in the report to the Committee of Action and to send letter to Sector Board 3 regarding the expected enormous amount of work related to the validation of new requested DETs and to express our concern about the amount of work to be performed by volunteers.

Mr. Satoshi Ito informed the working group via a presentation about the in Japan running ChemICALS and E-CALS and E-CALSII.

The E-CALSII project runs through March 2000. Goals:

- 90 new major classes to be added;
- develop an EC (electronic commerce) environment;
- establish a resource centre.

Mr. Ito will investigate if an electronic version of the available information may be made available in SPF format to the working group, in which case Dr. Radley will see if with available tools the information can be converted into other wanted data formats.

working group 1

The proposal regarding the classification of geometry's, based on the results of the last working group meeting, was discussed, amended and accepted. The classification was detailed and the new needed geometry classes were defined.

The linking mechanism from the geometry class towards the relevant drawing was established.

The secretary will incorporate the modifications and proposals into a new CD to be circulated early 1999 in time before the next working group meetings.

5 New activities

Currently no new activities will be undertaken other than that are already indicated in this report. The lack of human power still remains the largest problem.

6 Discussion document 3(Charlottenlund/Germany)14

Although the working group welcomes the ideas about avoiding overlap in work improving of the efficiency as stated in the document, we believe that there exists a misconception about the contents of the work items and workload of SC3D reading the justification arguments in the green paper. The working group members are unanimous not in favour of the stated proposals.

7 Planned working group meetings

Next working group meetings are scheduled:

March 1999 Muenchen, Germany

June 1999 Sheffield, United Kingdom

October 1999 Kyoto in conjunction with the IEC general meeting.



Peter van Reekum
Convenor SC3D / WG 1&2
November 11th, 1998

Annex C



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3/532/INF
INFORMATION (INF)
1998-10

INTERNATIONAL ELECTROTECHNICAL COMMISSION

Technical Committee No. 3 Documentation and graphical symbols

Report from the liaison officer to IEC TC93 Design automation

After the TC3 meeting in New Delhi no new documents of interest to IEC TC3 have been identified. The following overview lists those ongoing activities relevant to IEC TC3.

1 Documents distributed within IEC TC 93

- PWI 93/50/NP Core model of electronics design (CMED); approved; related to harmonisation of connectivity models;
- PWI 93/73/NP Libraries of reusable parts for electrotechnical products; not sufficient participation; put to zero stage again;
- PWI 93/80/NP Electronic CAD to CAM Exchange; rejected;
- ANW IEC 62016 Design automation reference model - Core conceptual model of the electronics domain; related to harmonisation of connectivity models with ISO 10303-210 (and 212); no progress;
- PWI 93/75/FDIS IEC 61690-1 Electronic design interchange format (EDIF) V 300;
- CCDV 93/74/CDV IEC 61690-2 Electronic design interchange format (EDIF) V 400;

No progress has been made with respect to co-operation between 61690 series development and the relevant STEP developments, primarily ISO 10303-210.

2 Participation of IEC TC93 in Sector Board 3 / related ACET issues

- TC93 was invited from the CA to be member of the Sector Board 3, Industrial Automation. During the Sector Board 3, AHG1 meeting in Geneva in Feb. 1998, the Chairman of IEC TC 93 expressed that IEC TC93 objectives are focussed and limited to the software industry companies only, supplying CAx tools for the design, simulation and manufacturing of PWAs (printed wiring assemblies). It was confirmed that it was not the focus of IEC TC93 to support the interest of users of such tools nor to enter into other application areas.

The Chairman stated that he therefore considered IEC TC 93 not to be a committee for membership in Sector Board 3 as not being involved with industrial automation matters. Other SB3 members stated that industrial automation requires a consistent data flow from a PCB interface in a PLC assembly used for industrial automation processes. The policy of TC93 would not support this. The differences in policies were noted.

The present SPS of IEC TC93 covers the whole range of life cycle processes of industrial design, manufacturing, etc. covering all possible industry fields etc.

- Several SB3 members objected against PWI 93/73/NP as the PWI wording was considered to incorporate all committees requirements; therefore it was requested that the PWI should be more concisely written. It was discussed within SB3 AHG1 to recommend to set up a task force which

should identify the common requirements to all committees possibly involved, dealing with library issues.

Unfortunately these discussion issues did not appear in the SB3 reports, nor have they been correctly transmitted to the ACET meeting in April 98. None of the ACET meeting participants has been present in the relevant SB3 meeting. The document ACET/176/RM provides therefore in the report a recommendation 9804/16 which does not correctly reflect the concerns of the SB3 members.

F. Reuter

Liaison Officer

Annex D



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3D(Charlottenlund/Kisselmann)07
November 1998

INTERNATIONAL ELECTROTECHNICAL COMMISSION

SUB-COMMITTEE NO.3D: DATA SETS FOR LIBRARIES OF ELECTRIC COMPONENT DATA

Report of the liaison with CIREP Esprit Project

CIREP Overview

Duration : 30 months
Started 1st of July, 1996
5 Mecu project

CIREP objectives

To produce methodologies for creating Component descriptions and building libraries of Component Information where the user of components can get the component information he needs for construction, production, maintenance and recycling his products, and the producer can deliver his datas

CIREP Meetings:

Main meetings held during the reporting period are the following:

2nd CIREP Review by the EC - BRUSSELS: December 9th and 10th 1997

CIREP-Integration Meeting in Marseille : April 22nd - 24th 1998 at Euritis

CIREP-Demonstration preparation Meeting in Paris : June 30th 1998 at Spring

3rd CIREP Review Meeting in Hagen: July 7th , 1998

CIREP-Meeting in Paris, Sept 15th and 16th, 1998

Next meetings

CIMT/CICT Workshop in Hagen, November 25th and 26th, 1998

4th CIREP Review January 14th , 1999 in Paris

Use of IEC 61360 in CIREP

From the outset, CIREP proposed to use the results of the SC3D work for several reasons, among which were the prospect of a basic dictionary and classification scheme and the fact that an information model in EXPRESS was under development, which would be compatible with the CIREP methodology. In the event, both the dictionary and the EXPRESS model became available during the project.

The existence of the dictionary and classification scheme has been very helpful in CIREP in the three demonstrator classes (DRAMs, Zener Diodes and Capacitors). It has enabled definition of information requirements for those classes and the construction of CIREP CDILs to be undertaken quite quickly. Even though not all properties needed to describe the components for each class are currently in the dictionary, it has proved possible to define new properties according to the methodology of IEC 61360 and these will, be offered to the IEC as candidates for inclusion in an expanded dictionary.

The information model for the CDILs and family instances in CIREP has been written in EXPRESS and uses the information model from IEC 61360 Part 2 with extensions from the PLIB series of standards. As a result, CIREP has provided the first live application of the IEC 61360 series of standards.

Procedures are now well established for generating all or part of the IEC dictionary in STEP Physical File Format (SPFF), which is the neutral format agreed by CIREP, in a form which has been shown to comply with the EXPRESS model. Also, the CIREP information model is embedded in the CIMT/CICT tools for component information modeling and data capture.

CIREP Exploitation of results

All partners are currently refining plans for integrating project developments into their global strategy for component information libraries within their CIME environment and bringing to an industrial stage the pilot exploitation developed in CIREP.

ECIX, the US based «electronic data book» project, is adopting CIREP technology based on the IEC61360 standard.

The user group has been extended, and will be further extended as soon as a CIREP attractive documentation and demonstrator will be available. During the discussions the most important question was: How will the CIREP standard be maintained?

Wolf-Dieter Kisselmann
Charlottenlund, Nov 12th, 1998

CDIL = Class Data Item List
CIHS = Component Information Handling System
ECIX = Electronic Component Information eXchange
CIMT / CICT = component information modelling and capture tool
SPFF =STEP Physical File Format

Annex E



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November

INTERNATIONAL ELECTROTECHNICAL COMMISSION

SUB-COMMITTEE NO.3D: DATA SETS FOR LIBRARIES

Report of the liaison with Cenelec TC 217 and SI2-ECIX

1 Cenelec TC 217

The statement I made in the report of last year that most of the activities/projects have been finished caused an "on hold" situation.

Since July 1997 no meeting took place; no further information available on open activities.

1.1 Relevant topics in relation to SC3D

The for SC3D related topic was covered under WG 4 as item 4.4 Electronic Data Book Interchange Format (CLC Project: 5911). A number of editorial updates have caused a delay. The documents R217-015, R217-016, ENV 50247-1 and ENV 50247-2 are offered for publication to the CENELEC Central Secretariat on October 15th, 1998. The earlier indicated Copyright and IPR issues are settled between CENELEC and SI2.

2 SI2 - ECIX

2.1 PCIS - CIDS:

Within the **ECIX** project the **PCIS** (Pinnacles Information Dictionary Standard) and the **CIDS** (Component Information Dictionary Standard) activities are further developed. During the Design Automation Conference in July 1998 a demonstrator was available in which the co-operation between the two sgml applications were showed.

The underlying dictionary of PCIS, the CIDS dictionary, was filled with the IEC 61360-4 information. CODUS provided a SFF file which was converted into SGML. Currently no other dictionaries are implemented in CIDS, however there are plans to do so.

A successful demonstration was also given at the DAC of the co-operation and interchange of dictionary data between ECIX and the ESPRIT CIREP project.

A handwritten signature in black ink, appearing to read 'F. van Noesel', written over a diagonal line.

Frans van Noesel
November 12th, 1998

Annex F



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3(Charlottelund/Secretariat)16A

INFORMATION
1998-11

INTERNATIONAL ELECTROTECHNICAL COMMISSION

Technical Committee No. 3 Documentation and graphical symbols

Preliminary plan for the meeting in Kyoto 1999

The following preliminary plan was submitted 1998-08-25 to the JISC for the meetings in Kyoto.

Thu 21 st	Fr 22 nd	Sat 23 rd	Mon 25 th	Tue 26 th	Wed 27 th	Thu 28 th	Fri 29 th
SC3B 30 pers.	SC3B 30 pers.	Sun 24 th	MT 60617 12 pers.	MT 60617 12 pers.			
	SC3C/JWG11 12 pers.		SC3C 20 pers.	SC3C 20 pers.			
	SC3D/WG1 12 pers.		SC3D/WG2 12 pers.	SC3D 20 pers.			
					TC3 workshop 40 pers.	TC3 40 pers.	TC3 40 pers.

Proposed new plan

Thu 21 st	Fr 22 nd	Sat 23 rd	Mon 25 th	Tue 26 th	Wed 27 th	Thu 28 th	Fri 29 th
SC3B 30 pers.	SC3B 30 pers.	Sun 24 th		VT 60617 10 (?) pers.			
	SC3C/JWG11 12 pers.			SC3C 20 pers.	SC3C 20 pers.		
	SC3D/WG1 12 pers.			SC3D/WG2 12 pers.	SC3D 20 pers.		
				TC3 workshop 40 pers.			TC3 40 pers. a.m. only

Revision A: Changes introduced at the meeting of TC3: SC3B mtg Fri 22nd omitted since all liaisons are to be dealt with at the TC3 mtg. TC3 mtg Fri 29th shortened to 1/2 day. A first meeting with the Validation Team for IEC 60617 introduced.

As a result of further considerations after the meeting the TC3 Workshop is suggested to be moved from Wed. 27th to Mon 25th, and the former meetings on Mon 25th and Tue 26th moved to Tue 26th and Wed 27th accordingly.

SEABB/KS 19087-719 3(chd-secr)16 plan for kyoto
Created: 98-11-11, Printed: 98-11-20
Keywords: tc3, plan, kyoto